

Title (en)

IMPROVED METHOD FOR PRODUCING A LAMINATED LAYER COMPOSITE AND COMPOSITE

Title (de)

VERBESSERTES VERFAHREN ZUR HERSTELLUNG EINES LAMINIERTEN SCHICHTVERBUNDES UND SCHICHTVERBUND

Title (fr)

PROCÉDÉ AMÉLIORÉ DE PRODUCTION D'UN COMPOSITE MULTICOUCHE LAMINÉ ET LAMINÉ

Publication

EP 2396172 A1 20111221 (DE)

Application

EP 10702440 A 20100130

Priority

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Abstract (en)

[origin: EP2218579A1] The method for the production of a laminated layer composite having a base layer (3) made of thermoplastic polymeric material with a vicat softening temperature and a further layer made of thermoplastic polymeric material, which has a low vicat softening temperature than the thermoplastic polymeric material of the base layer and if necessary a cover layer (5) made of thermoplastic polymeric material, comprises laminating the layer composite at a temperature above vicat softening temperature of the further layer, which has maximum 5[deg] C above the vicat softening temperature of the base layer. The method for the production of a laminated layer composite having a base layer (3) made of thermoplastic polymeric material with a vicat softening temperature and a further layer made of thermoplastic polymeric material, which has a low vicat softening temperature than the thermoplastic polymeric material of the base layer and if necessary a cover layer (5) made of thermoplastic polymeric material, comprises laminating the layer composite at a temperature above the vicat softening temperature of the further layer, which has maximum 5[deg] C above the vicat softening temperature of the base layer, and then laminating at a temperature above the vicat softening temperature of the base layer. A component is contained between the base layer and the further layer. The vicat softening temperature of the further layer is 10[deg] C lower than the vicat softening temperature of the base layer. The component is electronic component or hologram. The electronic component is an integrated circuit, thick film circuits, circuit having discrete active and passive electronic component, sensors, chip module, displays, battery, coils, capacitor, conductor path and/or contact points. The thermoplastic material of the cover layer has a vicat softening temperature, which is higher than the vicat softening temperature of the further layer. An independent claim is included for a laminated layer composite.

IPC 8 full level

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